



GROUP 1700

MAY 10 2003

RECEIVED

500.39825X00

4/13/c
SA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al

Serial No.: 09/800,495

Filed: March 8, 2001

For: METHOD OF DETECTING AND MEASURING ENDPOINT OF POLISHING PROCESSING AND ITS APPARATUS AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE USING THE SAME

Group: 1765

Examiner: L. Umez Eronini

AMENDMENT

Mail Stop Fee-Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

May 15, 2003

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated January 15, 2003.

IN THE CLAIMS:

Please amend claims 1, 2, 9 and 10 as follows:

1. (twice amended) A method of detecting an endpoint of polishing processing, comprising the steps of:
simultaneously irradiating onto a film formed on a surface of a wafer under
polishing processing lights having different wavelengths from one another;
detecting reflected lights of different wavelengths from said film caused by the
irradiation with the lights of the different wavelengths; and